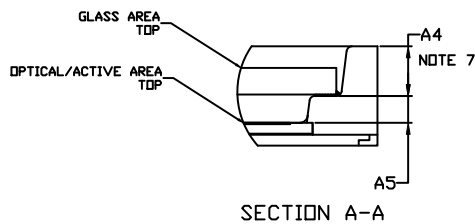
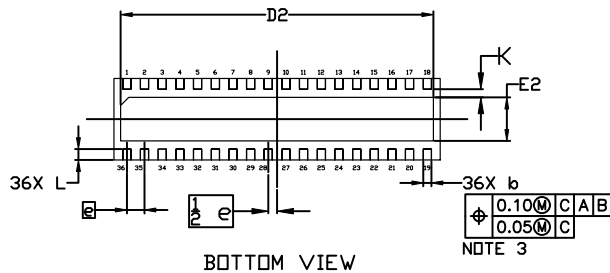
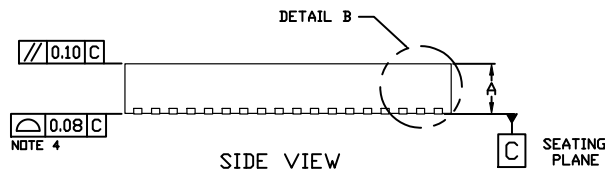
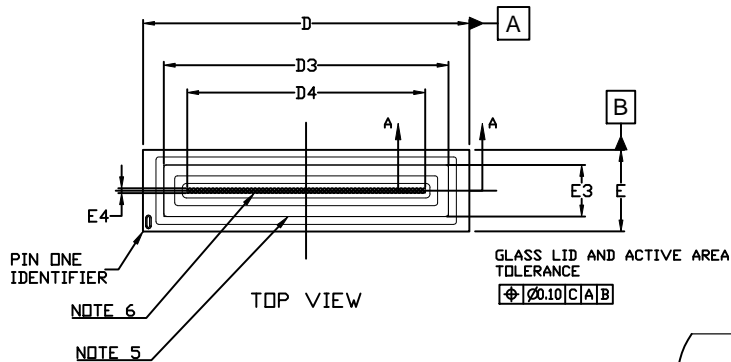


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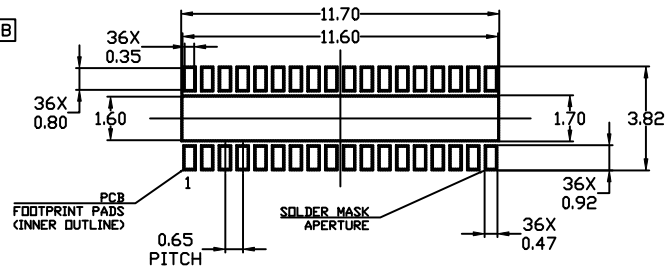
DATE 11 DEC 2020



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. GLASS LID AREA, 0.4mm THICKNESS. DEFINED BY D3 & E3.
6. OPTICAL/ACTIVE AREA IS CENTERED.
7. GLASS LID PLACEMENT. OUTER FLAT AREA APPROXIMATELY SIMILAR TO LID WIDTH AND LENGTH.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	1.75	1.85	1.95
A1	0.00	---	0.05
A3	0.203 REF		
A4	0.927 REF		
A5	0.500 REF		
b	0.25	0.30	0.35
D	11.90	12.00	12.10
D2	11.40	11.50	11.60
D3	10.47 REF		
D4	8.753 REF		
E	2.90	3.00	3.10
E2	1.50	1.60	1.70
E3	1.90 REF		
E4	0.18 REF		
e	0.65 BSC		
K	0.10	---	---
L	0.35	0.40	0.45



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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